

Specifications

Insulation Resistance: Dielectric Withstanding Voltage: 100V AC for 1 minute

Contact Resistance:

Operating Temperature Range:

Contact Force:

Actuation Force:

1,000M Ω min. at 100V DC

 $100m\Omega$ max. at 10mA/20mV max.

-40°C to +150°C

58.8mN (6gf) per pin approx.

29.6N (3kg)

Materials and Finish

Housing: Polyetherimide (PEI), glass-filled

Polyethersulphone (PES), glass-filled

Contacts: Beryllium Copper (BeCu)

Gold over Nickel Plating:

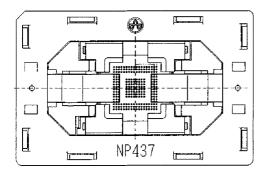
Features

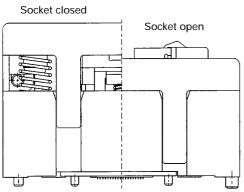
Open top socket for BGA / LGA / CSP packages with 0.4mm pitch. 22 x 22 maximum grid size and 11 x 11 maximum body size

Depopulation versions available

Compression mount 0.4 to 0.6mm fan-out type

Outline Socket Dimensions





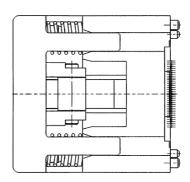


Top View from Socket

□ Part Number (Details)



Please Contact Yamaichi



☐ Typical IC Grid Size 22 x 22 (max.)

